

ES51C1 A 15 V -10.000M TR Packaging Options Tape & Reel

Nominal Frequency

10.000MHz



Operating Temperature Range 0°C to +50°C

Control Voltage 1.5Vdc ±1.0Vdc

Frequency Stability -±1.5ppm Maximum

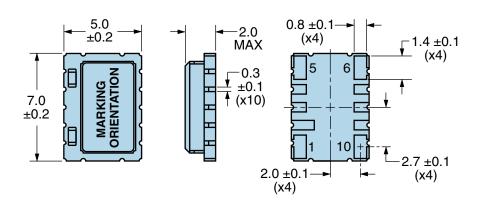
	10.000MHz ±1.0ppm Maximum (Measured at 25°C ±2°C, Vdd=5.0Vdc, Vc=1.5Vdc)
	+1 000m Maximum (Massured at 25°C +2°C)/dd=5 0 /dc)/c=1 5//dc)
TOIETAILCE	
Frequency Stability :	±1.5ppm Maximum
Frequency Stability vs. Input Voltage	±0.2ppm Maximum (Vdd ±5%)
Frequency Stability vs. Aging	±1ppm/Year Maximum (at 25°C)
Frequency Stability vs. Load	±0.2ppm Maximum (±1kOhm//±1pF)
Operating Temperature Range	0°C to +50°C
Supply Voltage	5.0Vdc ±5%
Input Current	1.5mA Maximum
Output Voltage	0.8Vp-p Clipped Sinewave Minimum
Load Drive Capability	10kOhms//10pF
Output Logic Type	Clipped Sinewave
Control Voltage	1.5Vdc ±1.0Vdc
Frequency Deviation	±8ppm Minimum
Linearity	10% Maximum
Transfer Function	Positive Transfer Characteristic
Modulation Bandwidth	3kHz Minimum (Measured at -3dB with a Control Voltage of 1.5Vdc)
Input Impedance	100kOhms Minimum
	-80dBc/Hz at 10Hz offset, -115dBc/Hz at 100Hz offset, -135dBc/Hz at 1kHz offset, -145dBc/Hz at 10kHz offset, -145dBc/Hz at 10kHz offset, -145dBc/Hz at 10kHz offset (Typical Values, at 12.800MHz)
Start Up Time	5mSec Maximum
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A



MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Voltage Control
2	Do Not Connect
3	Do Not Connect
4	Do Not Connect
5	Case/Ground
6	Output
7	Do Not Connect
8	Do Not Connect
9	Do Not Connect
10	Supply Voltage
LINE	MARKING
1	E10.000 E=Ecliptek
2	XXYZZ XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year

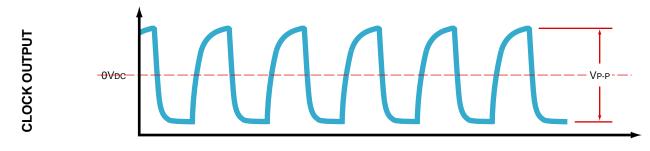
Suggested Solder Pad Layout

All Dimensions in Millimeters \rightarrow 1.2 (X4) 1.8 (X4) 3.9 3.0 3.04

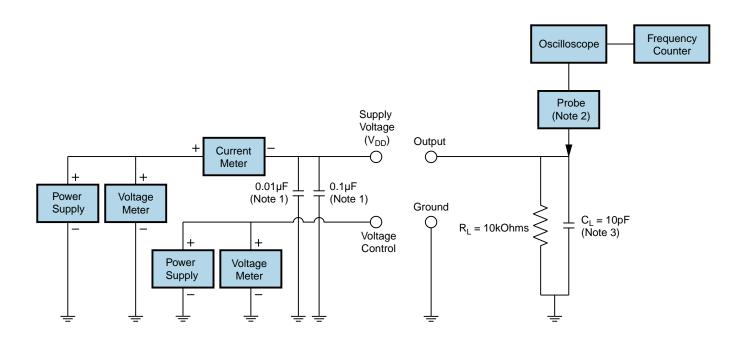
All Tolerances are ±0.1



OUTPUT WAVEFORM



Test Circuit for Voltage Control Option



Note 1: An external 0.1µF low frequency tantalum bypass capacitor in parallel with a 0.01µF high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

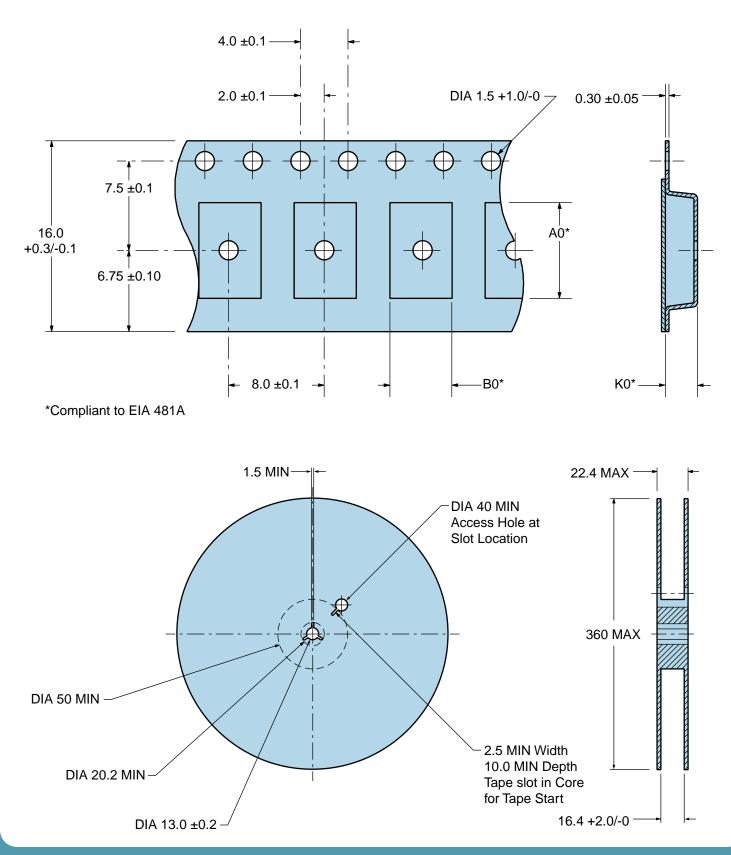
Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.



Tape & Reel Dimensions

Quantity Per Reel: 1,000 units



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Recommended Solder Reflow Methods

ES51C1A15V-10.000M TR



Low Temperature Infrared/Convection 220°C

T _s MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	60 - 120 Seconds
Ramp-up Rate (T⊾ to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T₋)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T _P)	220°C Maximum
Target Peak Temperature (T _P Target)	220°C Maximum 1 Time / 215°C Maximum 1 Time
Time within 5°C of actual peak (t _p)	15 seconds Maximum 1 Time / 80 seconds Maximum 1 Time
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.